



Product Change Notification: MFOL-08KSAS331

Date:

16-May-2025

Product Category:

32-Bit Microcontrollers

Notification Subject:

CCB 7564 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected ATSAMC20G15A, ATSAMC20G16A, ATSAMC20G17A, ATSAMC20G18A, ATSAMC21G15A, ATSAMC21G16A, ATSAMC21G17A, ATSAMC21G18A, ATSAMD20G14, ATSAMD20G15, ATSAMD20G16, ATSAMD20G17, ATSAMD20G18, ATSAMD21G15, ATSAMD21G16x, ATSAMD21G17x, ATSAMD21G18, ATSAML21G16B, ATSAML21G17B and ATSAML21G18B device families available in 48L VQFN (7x7x0.9mm) package at MP3A assembly site.

Affected CPNs:

[MFOL-08KSAS331_Affected_CPN_05162025.pdf](#)
[MFOL-08KSAS331_Affected_CPN_05162025.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected ATSAMC20G15A, ATSAMC20G16A, ATSAMC20G17A, ATSAMC20G18A, ATSAMC21G15A, ATSAMC21G16A, ATSAMC21G17A, ATSAMC21G18A, ATSAMD20G14, ATSAMD20G15, ATSAMD20G16, ATSAMD20G17, ATSAMD20G18, ATSAMD21G15, ATSAMD21G16x, ATSAMD21G17x, ATSAMD21G18, ATSAML21G16B, ATSAML21G17B and ATSAML21G18B device families available in 48L VQFN (7x7x0.9mm) package at MP3A assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change
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Assembly Site	Microchip Technology Inc. (MPHIL-3) (MP3A)	Microchip Technology Inc. (MPHIL-3) (MP3A)
Wire Material	Au	CuPdAu
Die Attach Material	3280	3280
Molding Compound Material	G700LTD	G700LTD
Lead-Frame Material	C194	C194

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: June 2025

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: May 16, 2025: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[**PCN_MFOL-08KSAS331_Qualification_Plan.pdf**](#)

Please contact your local [**Microchip sales office**](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [**PCN home page**](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.